imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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1SS383T1G

Preferred Device

Dual Schottky Diode

Dual 40 V, 300 mA Low $V_{\rm F}$ Schottky Diodes in 4–lead SC–82 package.

Features

- Low Forward Voltage: $V_F = 0.48 \text{ V} (\text{typ}) @ I_F = 100 \text{ mA}$
- Low Reverse Current: $I_R = 5 \mu A (max)$
- This is a Pb–Free Device*

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Continuous Reverse Voltage	V _R	40	V
Maximum Peak Forward Current*	I _{FM}	300	mA
Peak Forward Surge Current Pulse Width = $10 \ \mu s$	I _{FM(surge)}	500	mA

THERMAL CHARACTERISTICS

Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P _D	200 (Note 1) 1.6 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	625 (Note 1)	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability. *Both Devices Active

1. FR-4 @ Minimum Pad.

Characteristic Symbol Min Max Unit Тур Forward Voltage V_{F} mV 280 $(I_{F} = 1.0 \text{ mA})$ _ 360 _ $(I_{F} = 10 \text{ mA})$ _ 540 600 $(I_{F} = 100 \text{ mÅ})$ **Reverse Current** I_R μA (V_R = 40 V) 5 _ _ Capacitance C_D pF 25 $(V_{\rm R} = 0, f = 1.0 \text{ MHz})$ _

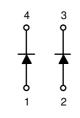
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

http://onsemi.com





SC-82 CASE 900AA

MARKING DIAGRAM



AE = Specific Device Code M = Date Code

= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
1SS383T1G	SC-82 (Pb-Free)	3000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

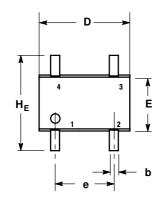
Preferred devices are recommended choices for future use and best overall value.

1SS383T1G

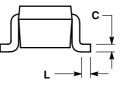
PACKAGE DIMENSIONS

SC-82, 4 LEAD, GULL WING

CASE 900AA-01 ISSUE O



A₁



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI 1. Y14.5M. 1982.
- CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD 3. FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUMTHICKNESS OF BASE MATERIAL
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.04
A 1	0		0.10	0		0.004
b	0.10	0.20	0.30	0.004	0.008	0.012
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.15	1.25	1.35	0.045	0.049	0.053
е	1.30 BSC		0.051 BSC			
HE	2.00	2.10	2.20	0.079	0.083	0.087
	0.10	0.20	0.30	0.004	0.008	0.012

STYLE 1: PIN 1. ANODE 1 2. ANODE 2 3. CATHODE 2 4. CATHODE 1

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